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(12) **United States Design Patent**  
**Matteson**

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(54) **SEMICONDUCTOR CHIP**

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(\*\*) **Term:** **14 Years**

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(51) **LOC (7) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Search** ..... **D13/105, 107, D13/114, 110, 117, 182; 174/52.1, 52.2, 52.4, 52.5; 361/679, 728, 736, 737, 742, 752, 802, 818; 257/679; 439/328, 377**

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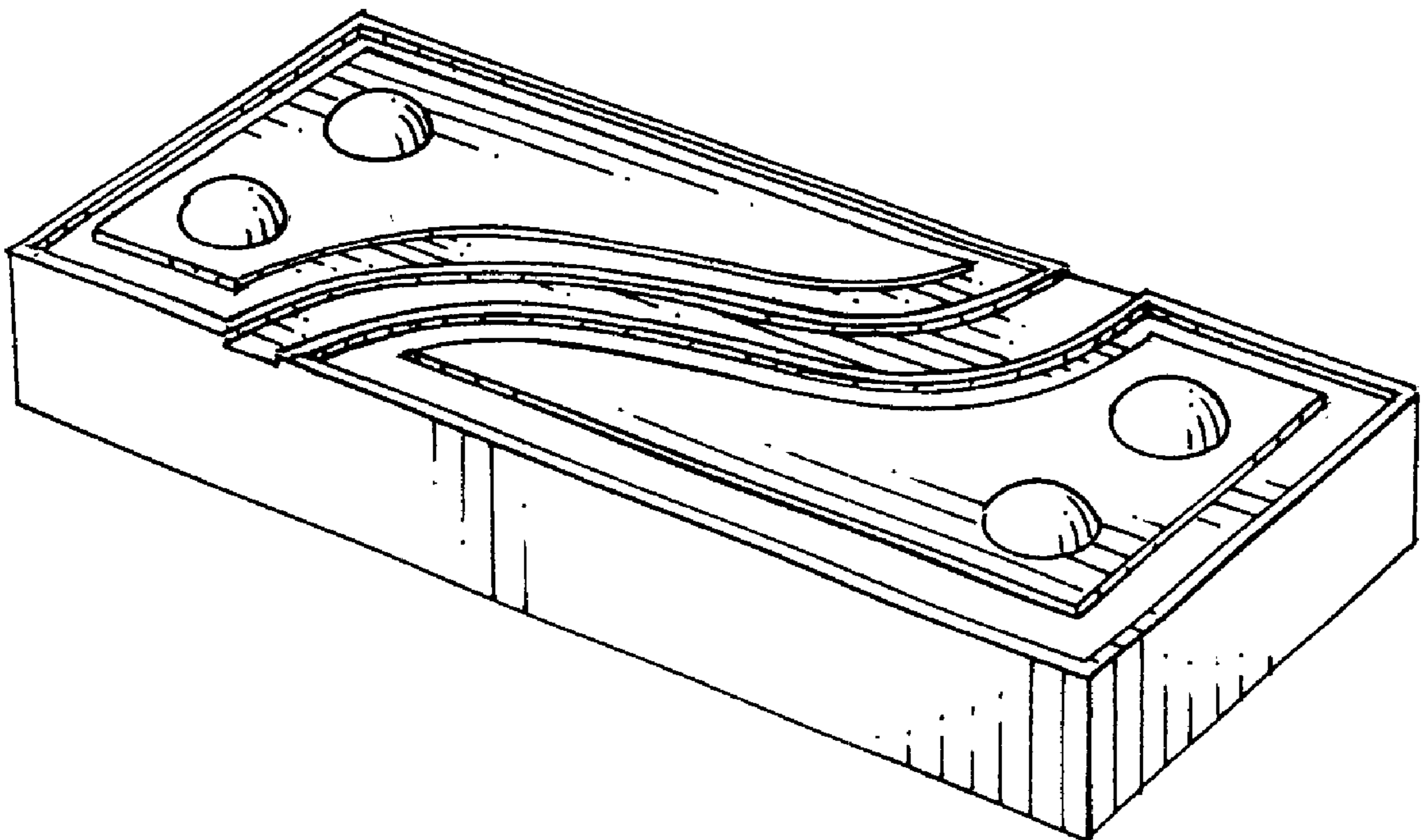
(57) **CLAIM**

The ornamental design for a semiconductor chip, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a semiconductor chip illustrating my new design;  
 FIG. 2 is a top view thereof;  
 FIG. 3 is a front elevational view showing one side of the semiconductor chip;  
 FIG. 4 is an end view of the semiconductor chip of FIG. 2 showing the left end thereof;  
 FIG. 5 is an end view of the semiconductor chip of FIG. 2 showing the right end thereof;  
 FIG. 6 is a side elevational view of the semiconductor chip of FIG. 2 showing a side opposite to that shown in FIG. 3; and,  
 FIG. 7 is a bottom view thereof.

**1 Claim, 1 Drawing Sheet**



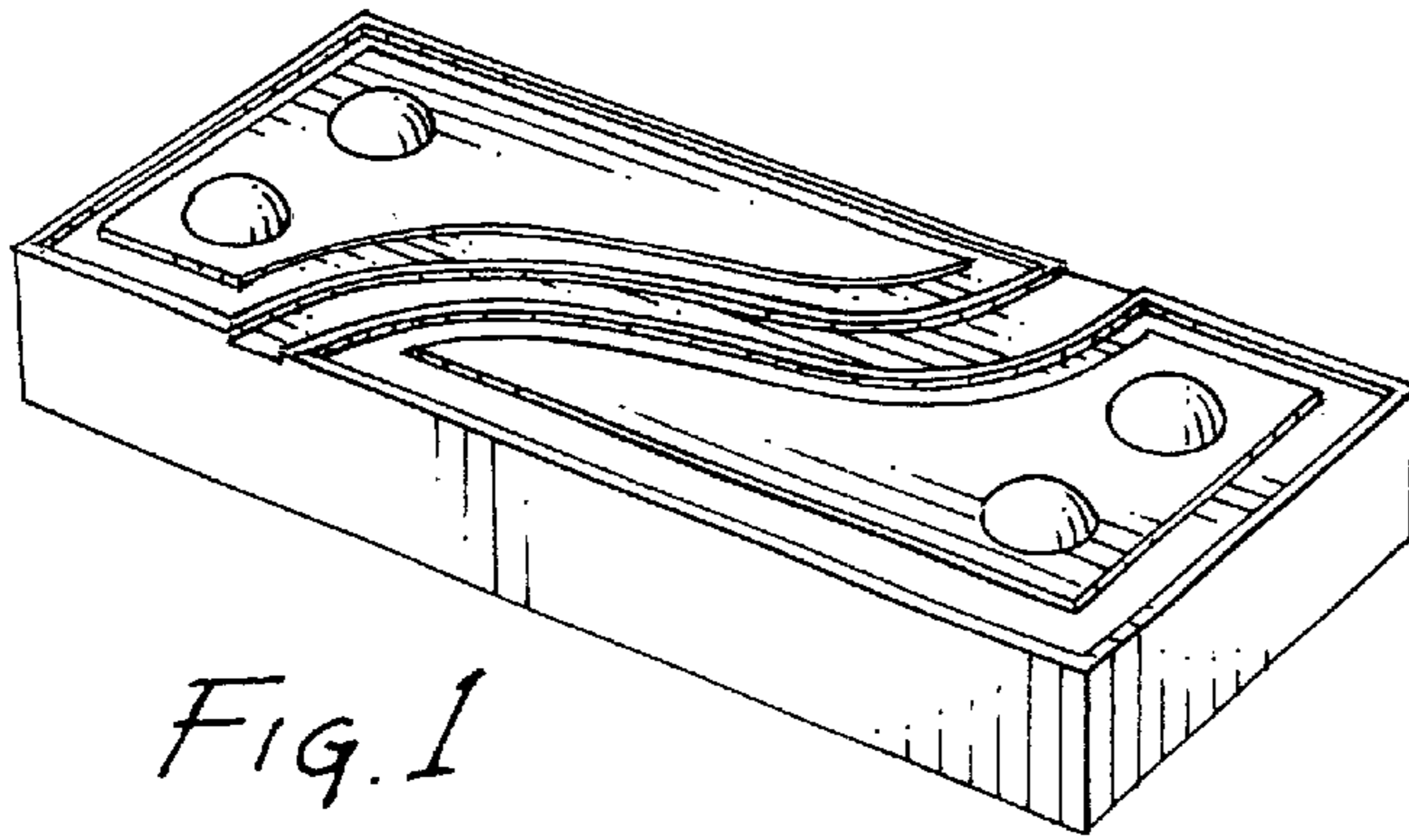


FIG. 1

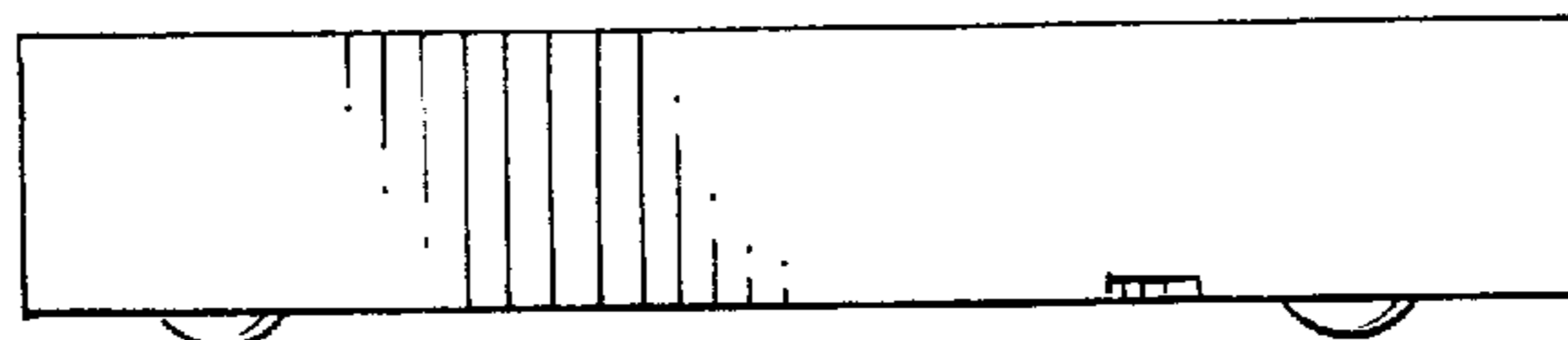


FIG. 3

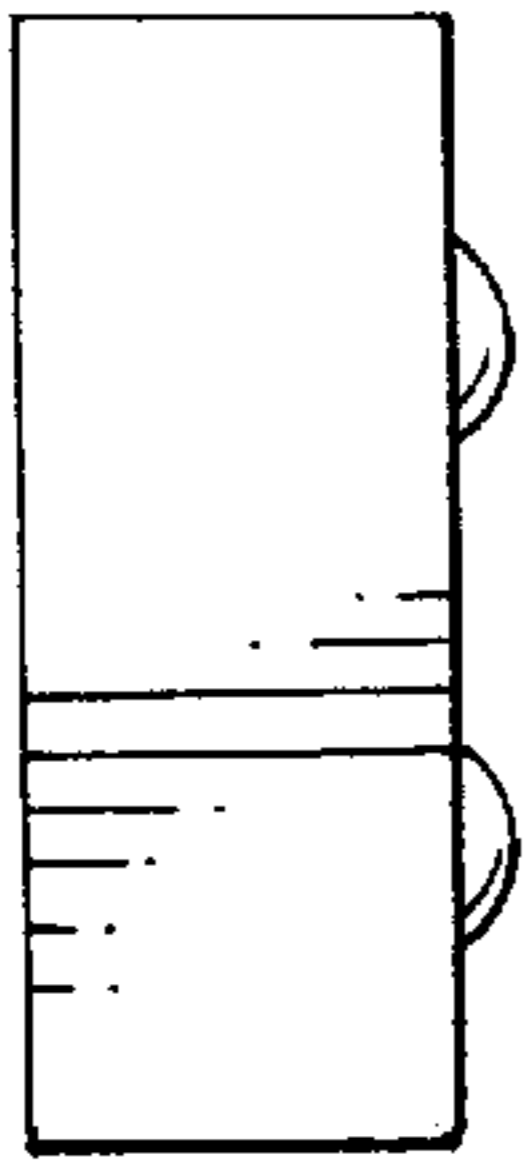


FIG. 4

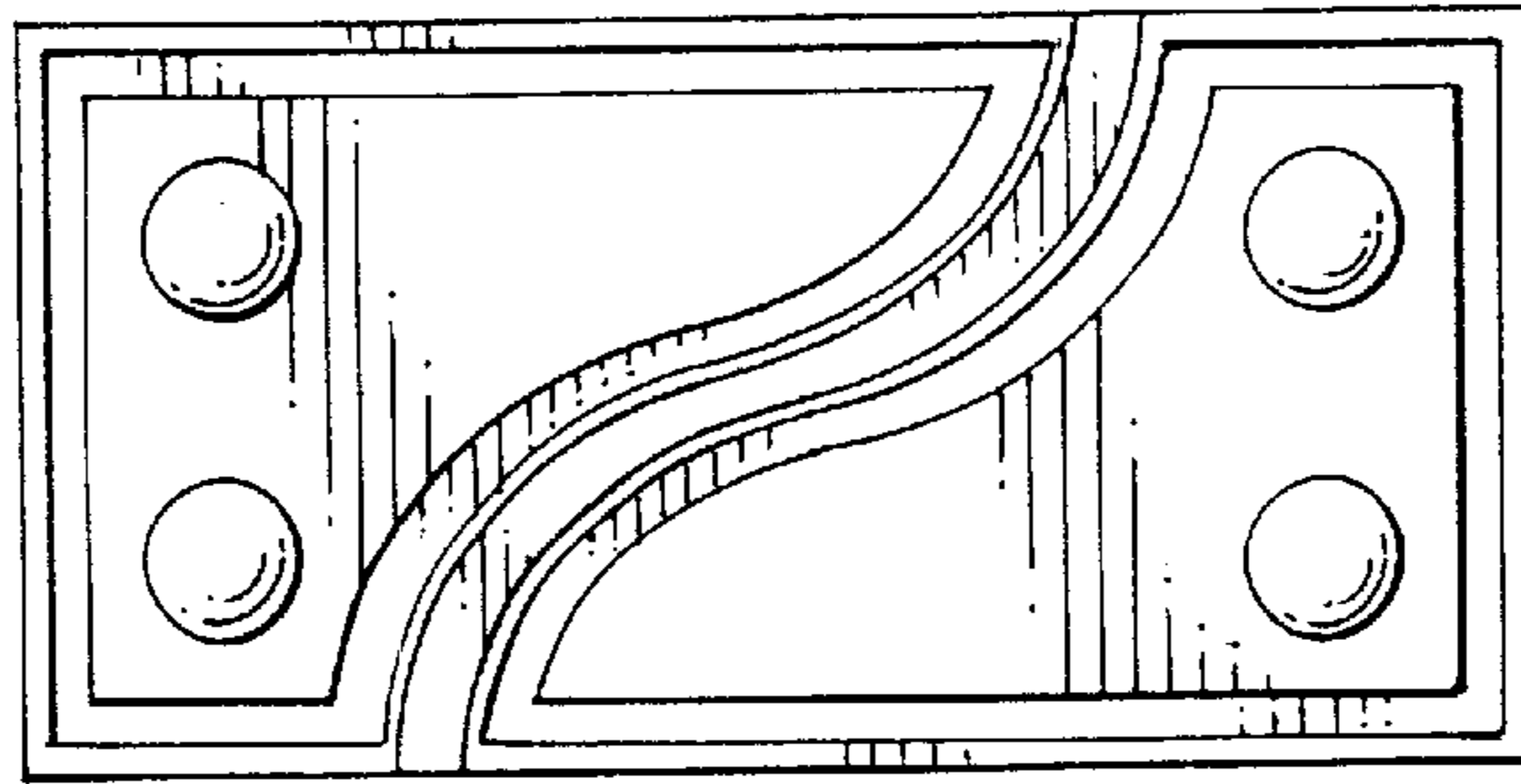


FIG. 2

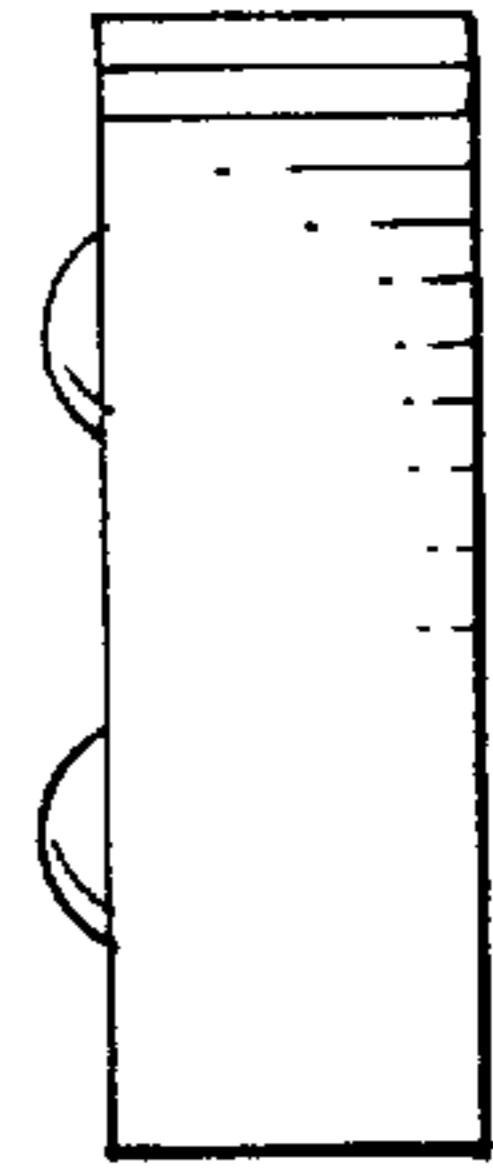


FIG. 5

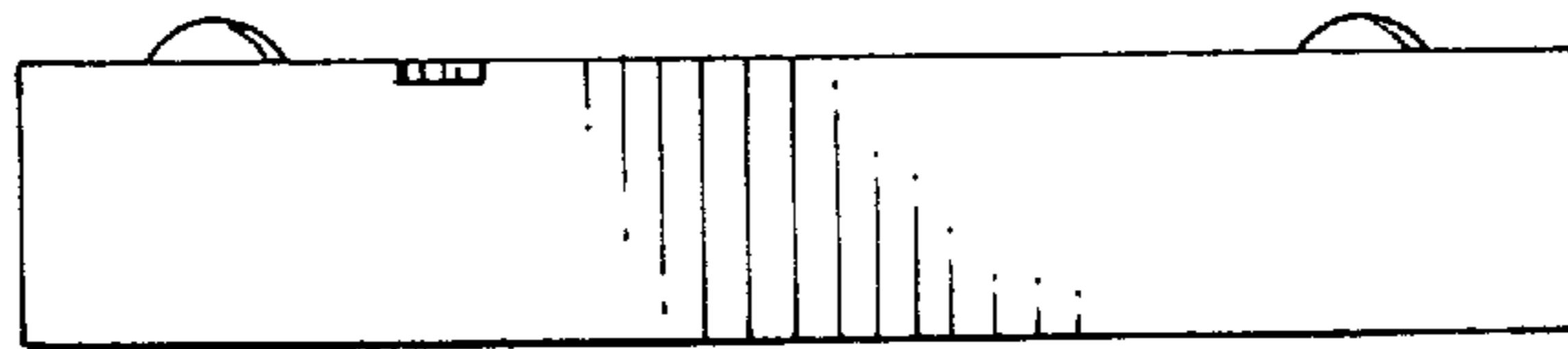


FIG. 6

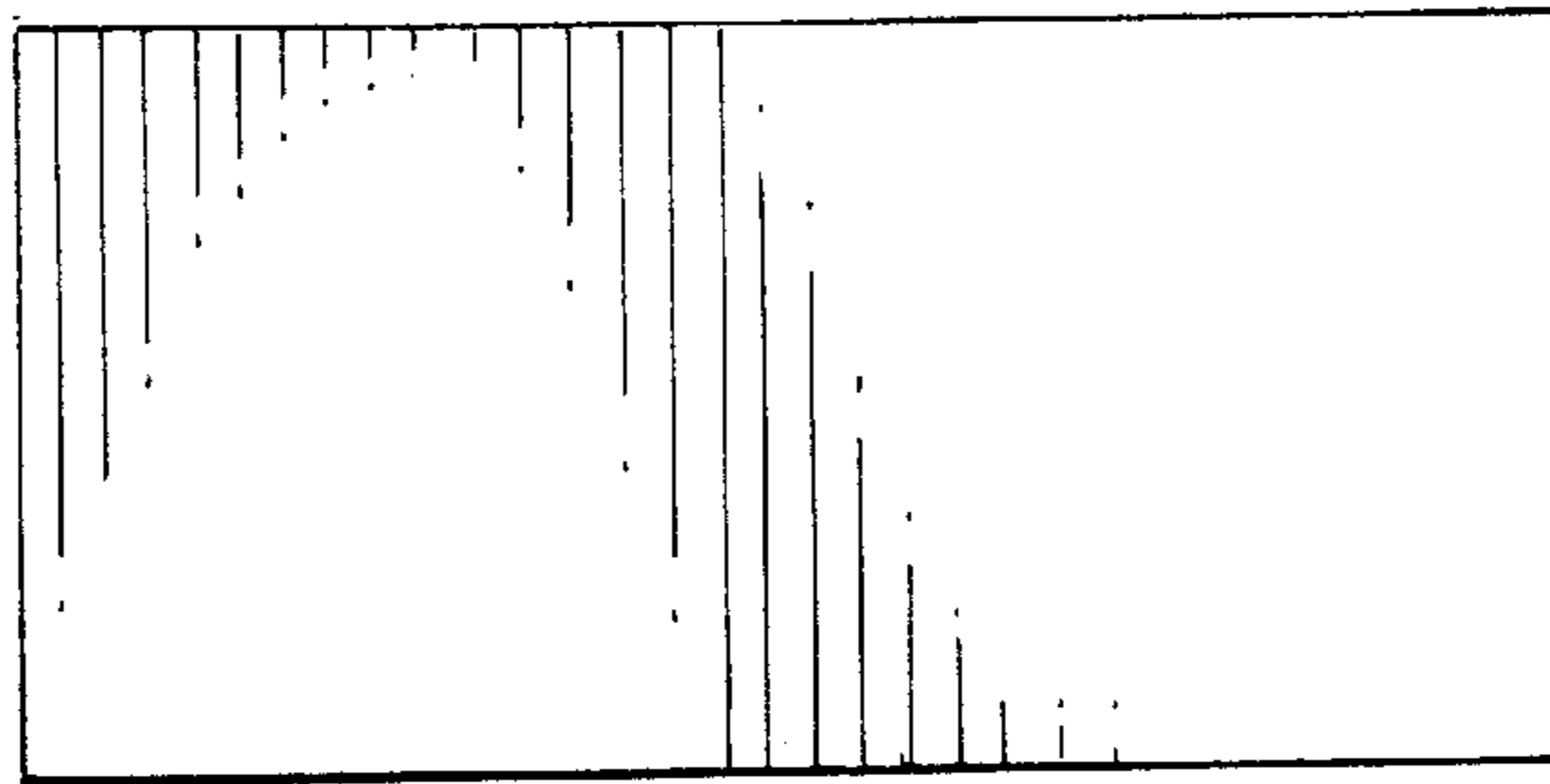


FIG. 7